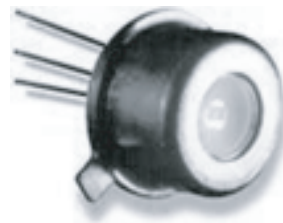
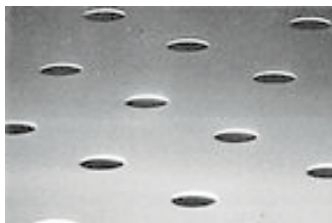


High Performance sLED for Datacommunication

HPsLED

Sheet 1 of 1

Telcom Devices Corporation introduces a surface light emitting diode for datacomm applications compliant with most LAN and WAN protocols, including Ethernet, ATM, FDDI, Escon and Fiber Channel. Data rates of up to about 625 Mbps are supported. A micro-machined lens formed directly in the InP die enhances optical coupling efficiency and reduces the cost of module assembly. The standard package is a lensed TO-18 header with isolated anode and cathode pins.



Micro-Machined Lens in InP Die Surface

ELECTRO OPTICAL SPECIFICATIONS

Parameters	Test Conditions	Minimum	Typical	Maximum	Units
CLASS 1 (155 Mb/s)					
Rise and Fall Time	100mA		2.3		ns
Link Bandwidth (–3dB)			155		MHz
Data Rate			270		Mbps
Coupled Optical Power	100mA, 62.5μm Fiber		35		uw
CLASS 2 (622 Mb/s)					
Rise and Fall Time			1		ns
Link Bandwidth (–3dB)			350		MHz
Data Rate			625		Mbps
Coupled Optical Power	100mA, 62.5μm Fiber		15		uw
RATINGS					
Peak Wavelength	100mA	1260	1300	1340	nm
Forward Voltage	100mA		1.3		V
Spectral Width (FWHM)	100mA		120		nm
Storage Temperature		–40		+85	C
Operating Temperature		–40		+85	C
Peak Forward Current			125		mA
Temperature Coefficient of Optical Power			–1		%/C
Temperature Coefficient Wavelength			0.6		nm/C

Sheet 1 of 1

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